

Final Product/Process Change Notification

Document #:FPCN21520ZI Issue Date: 06 Oct 2023

Title of Change:	Transfer of ONC25 technology to onsemi Aizu, Japan from current site onsemi Gresham, United States for NCV8730 and NCV8711 family.		
Proposed Changed Material First Ship Date:	13 Apr 2024 or earlier if approved by customer		
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered a orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletio of the current (unchanged) material inventory		
Product Category:	Active components – Integrated circuits		
Contact information:	Contact your local onsemi Sales Office or Jan.Gryzbon@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Sample Availability Date:	29 Sep 2023		
PPAP Availability Date:	29 Sep 2023		
Additional Reliability Data:	Contact your local onsemi Sales Office or <u>Vladislav.Hrachovec@onsemi.com</u>		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .		
Change Category			
Category	Type of Change		
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor		
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.		
Description and Democratic			

Description and Purpose:

This final notification announces the Transfer of ONC25 technology to onsemi Aizu, Japan from current site onsemi Gresham, United States.

The onsemi Aizu, Wafer Fab located at Aizuwakamatsu, Japan has been qualified to process the ONC25 CMOS process.

Tool sets are different but the exact same masking layers and steps are being used in the Aizu Fab.

This change is implemented to mitigate potential supply disruption; customers are encouraged to urgently review this change in order to minimize any potential impact to their supply chain.

	From	То
Wafer Fab Site	onsemi, Gresham, United States	onsemi, Aizu, Japan

There is no product marking change as a result of this change

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The affected products will be identified with date code and custom source.

Reason / Motivation for Change:	Source/Supply/Capacity Changes			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.			
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Aizu, Japan		None		

Reliability Data Summary:

QV DEVICE NAME: NCV8730ASN330T1G

Marking of Parts/ Traceability of Change:

RMS: S90290, S90289 **PACKAGE**: TSOP5

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/2400
Highly Accelerated Stress Test		130°C, 85% RH, 18.8psig, biased	96 hrs	0/240
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/240
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
Human Body Model (HBM)	JS001	2kV		pass
Charge Device Model (CDM)	JS002	1kV		pass
Latch-up (LU)	AEC-Q100-004, JESD78	Class II		pass
Electrical distribution	ON Data Sheet			pass

Note: AEC-1pager is attached.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file.

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
NCV8730ASNADJT1G	NA	NCV8730ASN330T1G
NCV8730ASN500T1G	NA	NCV8730ASN330T1G
NCV8711ASN330T1G	NA	NCV8730ASN330T1G
NCV8730ASN330T1G	NA	NCV8730ASN330T1G
NCV8711BMTWADJTBG	NA	NCV8730ASN330T1G
NCV8730BMTW500TBG	NA	NCV8730ASN330T1G
NCV8730BMTWADJTBG	NA	NCV8730ASN330T1G
NCV8730BMTW330TBG	NA	NCV8730ASN330T1G
NCV8711ASN500T1G	NA	NCV8730ASN330T1G
NCV8711ASNADJT1G	NA	NCV8730ASN330T1G
NCV8730ASN180T1G	NA	NCV8730ASN330T1G
NCV8711BMTW330TBG	NA	NCV8730ASN330T1G
NCV8730BMTW1500TBG	NA	NCV8730ASN330T1G
NCV8711ASN300T1G	NA	NCV8730ASN330T1G

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